

SUBMINIATURE SOLID STATE LAMP

Part Number: AM27EC03 High Efficiency Red

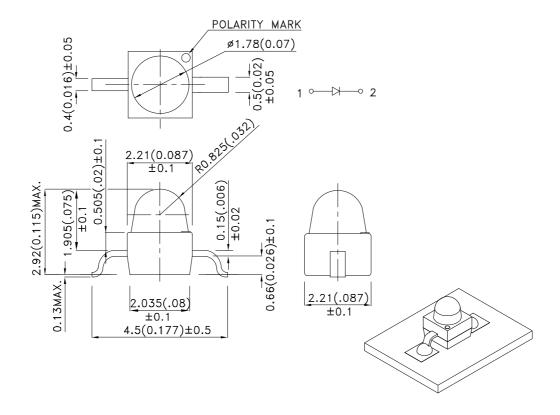
Features

- SUBMINIATURE PACKAGE.
- GULL WING.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- RoHS COMPLIANT.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.





 SPEC NO: DSAB5748
 REV NO: V.6
 DATE: MAY/08/2007
 PAGE: 1 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202000245

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM27EC03	High Efficiency Red (GaAsP/GaP)	WATER CLEAR	10	70	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627	nm IF=20mA		IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	V _F =0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red		10	uA	V _R =5V

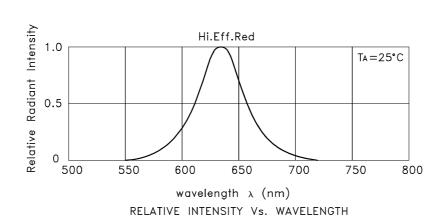
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

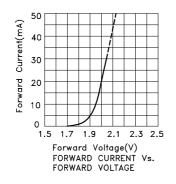
_	
igh Efficiency Red Units	Parameter
75 mW	Power dissipation
30 mA	DC Forward Current
160 mA	Peak Forward Current [1]
5 V	Reverse Voltage
-40°C To +85°C	Operating Temperature
-40°C To +85°C	Storage Temperature
-40°C To +85°C	Storage Temperature

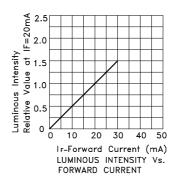
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

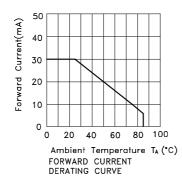
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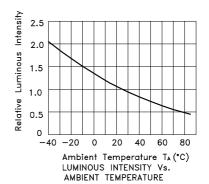


High Efficiency Red AM27EC03









1.0 40°

1.0 60°

70°

80°

90°

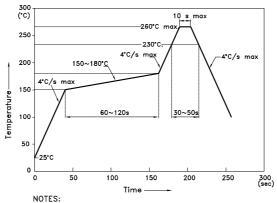
SPATIAL DISTRIBUTION

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AM27EC03

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

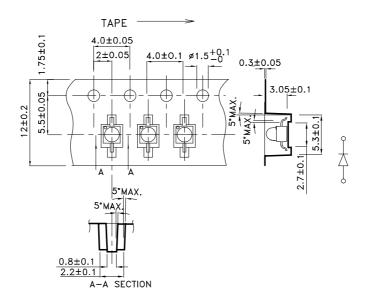
 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

3.0 1.6 1.6

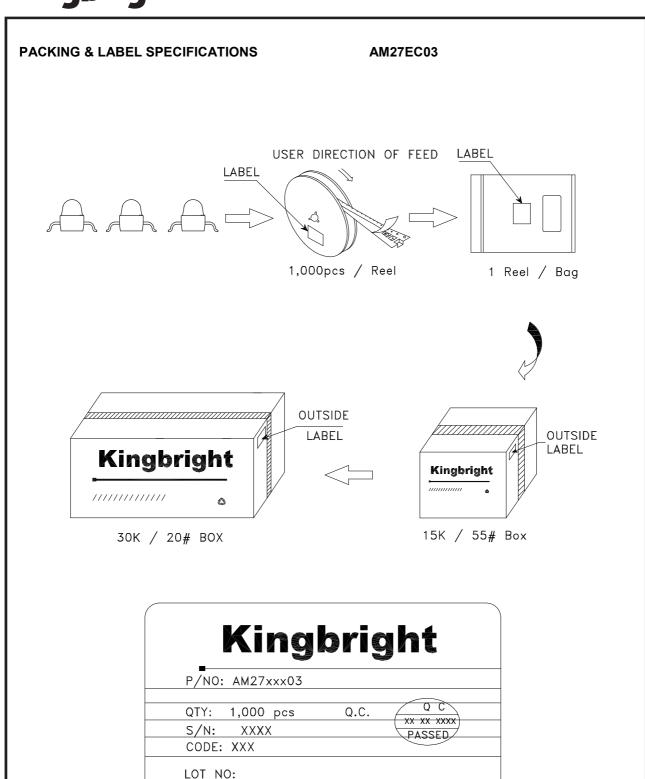
Tape Specifications (Units: mm)



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RoHS Compliant

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